

In the claims:

1-19. (Withdrawn)

20. (New) An article manufactured by an improved method for electroless plating of copper on a substrate using an electroless composition for electroless plating of copper on a substrate, said composition comprising copper ions, a complexing agent for Cu^{++} ions, a complexing agent for Cu^{+} ions, and a reducing agent capable of reducing copper ions to metallic copper and hydroxide ions to a pH of at least 10.

21. (New) An article manufactured by an improved method for electroless plating of copper on a substrate using an electroless composition for electroless plating of copper on a substrate, comprising copper ions, a mixture of complexing agents for Cu^{++} ions, a mixture of complexing agents for Cu^{+} ions, a reducing agent capable of reducing copper ions to metallic copper and hydroxide ions to a pH of at least 10.

22. (New) An article manufactured by an improved method for electroless plating of copper on a substrate using an electroless composition for electroless plating of copper on a substrate, said composition comprising copper ions, a complexing agent for Cu^{++} ions, a complexing agent for Cu^{+} ions, and a reducing agent capable of reducing copper ions to metallic copper and hydroxide ions to a pH of at least 10,

wherein said method further comprises heating the substrate to a temperature above the operating temperature of the electroless plating bath.

23. (New) The article of claim 22, wherein at least part of the surface of said substrate is non-metallic.